

**In the Specification:**

Please amend the paragraph on page 10, lines 26-33 as follows:

For the embodiments illustrated in **FIG. 3**, the landing pad type independent interconnection layer **145** is used as a contact plug that connects the upper electrode **133** of the MIM capacitor with the third interconnection layer **161**. Thus, a thick insulating layer, as compared to the conventional device of **FIG. 1**, including the first and second IMDs **141** and **155**, is disposed between the lower electrode ~~[[131]]~~ 127 of the MIM capacitor and the third interconnection layer **161**. As a result, more stable capacitance characteristics may be provided for the MIM capacitor.